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(54) Title: METHOD OF FABRICATION AND IMPLEMENTATION OF PROCESS CONDITION MEASUREMENT DEVICE

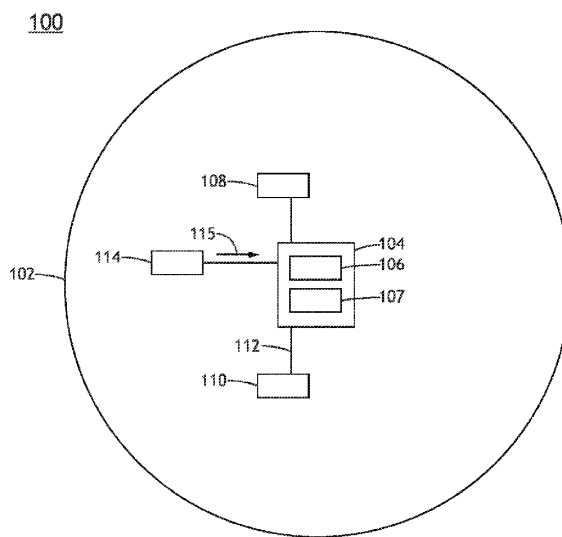


FIG. 1

(57) Abstract: A process condition measurement device may include a substrate made of a bottom substrate, a spacer, and a cover. The process condition measurement device may include a component. The component may be disposed within a cavity defined by the bottom substrate and a through hole defined by the spacer. The cover may be disposed above and cover the component. The cover may be a full cover or a partial cover. The component may also be disposed within a recess defined by the cover. The process condition measurement device may also include an insulation layer which encapsulates the component.

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